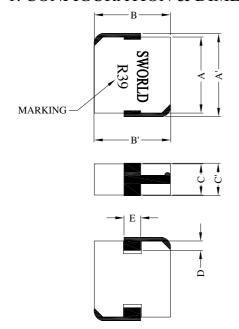
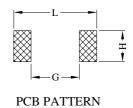
Product Name	HIGH CURRENT MOLDED POWER INDUCTORS	Page	1
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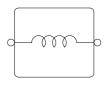
1. CONFIGURATION & DIMENSIONS:

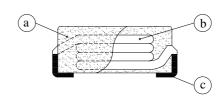


A': 7.8 MAX. m/m A: 6.86±0.5 m/m B': 7.0 MAX. m/m 6.47 ± 0.5 m/m 5.2 MAX. m/m 5.0 MAX. m/m D: 1.6±0.5 m/m E: 2.1 ± 0.5 m/m G: 3.7 REF. m/m H: 3.5 REF. m/m L: 8.7 REF. m/m



2. SCHEMATIC DIAGRAM:





3. MATERIAL LIST:

NO.	DESCRIPTION	SPECIFICATION	REMARK
a.	CORE	-	
b.	WIRE	-	
c.	TERMINAL	-	



NOTE: Specifications subject to change without notice. Please check our website for latest information.



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4. FEATURES:

- a. SHIELDED CONSTRUCTION
- b. FREQUENCY UP TO 5MHz

5. GENERAL SPECIFICATION:

a. TEST FREQ.: 100KHz/0.25VDC

b. AMBIENT TEMP.: 20°C

c. OPERATING TEMP. : -55°C ----- +125°C d. STORAGE TEMP. : -55°C ----- +125°C

e. HEAT RATED CURRENT (Irms) : WILL CAUSE THE COIL TEMP. RISE APPROXIMATELY $\Delta T {=} 40^{\circ} C$ WITHOUT CORE LOSS.

f. SATURATION CURRENT (Isat): WILL CAUSE Lo TO DROP APPROXIMATELY 20% TYP.

g. PART TEMPERATURE (AMBIENT+TEMP. RISE): SHOULD NOT EXCEED 125°C

UNDER WORST CASE OPERATING CONDITIONS.

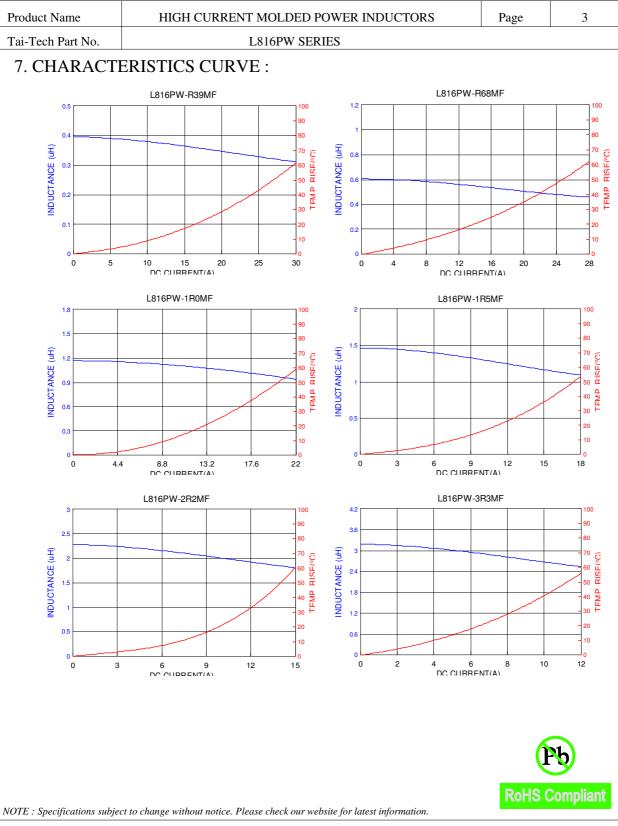
6. ELECTRICAL CHARACTERISTICS:

PART NO.	INDUCTANCE L ₀ (µH) ±20% @ 0 Adc	Irms (A) TYP.	Isat (A) TYP.	DCR (mΩ) MAX.
L816PW-R39MF	0.39	21	30	2.6
L816PW-R68MF	0.68	18	28	3.8
L816PW-1R0MF	1.00	15	22	4.2
L816PW-1R5MF	1.50	16	18	5.4
L816PW-2R2MF	2.20	13	15	8.2
L816PW-3R3MF	3.30	10	13	15.2
L816PW-4R7MF	4.70	7	10	18.6
L816PW-6R8MF	6.80	6	8	30.0
L816PW-100MF	10.0	5	6	44.5



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Product Name 4 HIGH CURRENT MOLDED POWER INDUCTORS Page Tai-Tech Part No. L816PW SERIES 7. CHARACTERISTICS CURVE: L816PW-4R7MF L816PW-6R8MF INDUCTANCE (uH) INDUCTANCE (uH) 70 (O₀)30 HISE (O₀)40 HISE 4 DC CURRENT(A) 4 6 DC CLIBBENT(A) L816PW-100MF INDUCTANCE (uH) 10 2 3 DC CLIRRENT(A)

RoHS Compliant

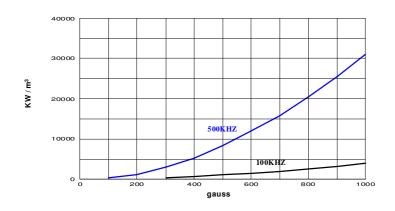
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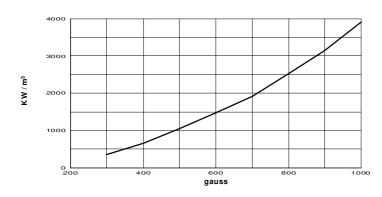
8. CORE LOSS:

100KHz AND 500KHz



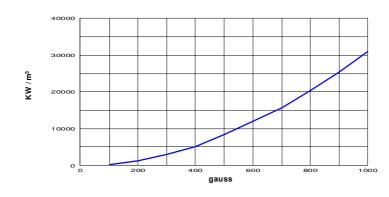
material gauss loss	100KHz	500KHz
100	-	266
200	1	1,234
300	351.7	2,932
400	665.9	5,195
500	1,039	8,336
600	1,471	12,025
700	1,923	15,715
800	2,537	20,444
900	3,148	25,429
1000	3,902	31,002

100KHz



material gauss loss	100KHz
300	351.7
400	665.9
500	1,039
600	1,471
700	1,923
800	2,537
900	3,148
1000	3,902

500KHz



material gaus loss	500KHz
100	266
200	1,234
300	2,932
400	5,195
500	8,336
600	12,025
700	15,715
800	20,444
900	25,429
1000	31,002



RoHS Compliant

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9. RELIABILITY AND TEST CONDITION:

ITEM	PERFORMANCE	TEST CONDITION
Electrical Characteristics	Гest	
Inductance	Refer to standard electrical characteristics list	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Heat Rated Current (Irms)		Irms(A) will cause the coil temperature rise approximately ΔT =40°C without core loss 1. Applied the allowed DC current 2. Temperature measured by digital surface thermomete
Saturation Current (Isat)		Isat(A) will cause Lo to drop approximately 20%
Mechanical Performance	Γest	
Solderability Test	More than 90% of the terminal electrode should be covered with solder.	Preheat: 150°C, 60sec. Solder: Sn99.95-Cu0.05 Solder Temperature: 230±5°C Flux for lead free: rosin Dip Time: 4±1sec. Preheating Dipping Natural cooling 150°C 1
Solder Heat Resistance	Appearance: No significant abnormality Inductance change: Within ±20%	Preheat: 150°C, 60sec. Solder: Sn99.95-Cu0.05 Solder Temperature: 260±5°C Flux for lead free: rosin Dip Time: 10±0.5sec. Preheating Dipping Natural cooling 150°C 150°C 150°C 10±0.5 seconds
Reliability Test		
High Temperature Life Test Low Temperature Life Test	Appearance : No damage	Temperature: 125±5°C Time: 500±12 hours Measure at room temperature after placing for 2 to 3 hrs Temperature: -55±5°C Time: 500±12 hours
	2. Inductance : Within ±20% of initial value.	Measure at room temperature after placing for 2 to 3 hrs
Thermal Shock	No disconnection or short circuit.	Conditions of 1 cycle. Step Temperature (°C) Times (min.) 1
Humidity Resistance	Appearance : No damage Inductance : Within ±20% of initial value. No disconnection or short circuit.	Temperature: 40±5°C Humidity: 90% to 95% Applied Current: Rated Curent Time: 500±12 hours Measure at room temperature after placing for 2 to 3 hrs

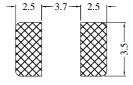
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10. SOLDERIND AND MOUNTING:

10-1. Recommended PC Board Pattern



10-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

10-2.1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

10-2.2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- a) Preheat circuit and products to 150°C.
- b) 280°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 3 secs.

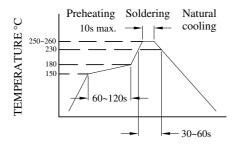


Figure 1. Re-flow Soldering

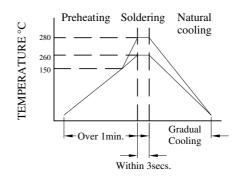


Figure 2. Iron Soldering



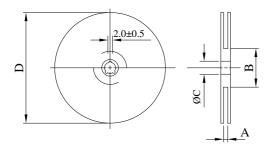
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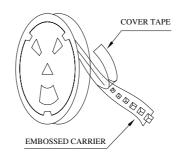


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11. PACKAGING INFORMATION:

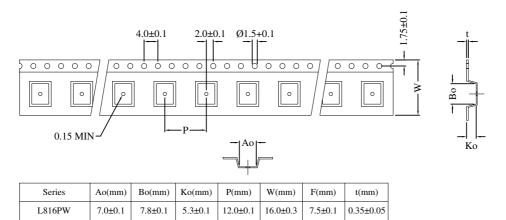
11-1. Reel Dimension





Type	A(mm)	B(mm)	C(mm)	D(mm)
13" x 16mm	16.0±0.5	100±2.0	13.5±0.5	330

11-2 Tape Dimension



11-3. Packaging Quantity

Size	L816PW	
Chip / Reel	800	
Inner Box	1600	
Carton	6400	

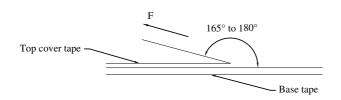
RoHS Compliant

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11-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300

Application Notice

1. Storage Conditions :

To maintain the solderabililty of terminal electrodes:

- a) Temperature and humidity conditions : Less than $30^{\circ} C$ and 70% RH.
- b) Recommended products should be used within 6 months from the time of delivery.
- c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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